



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20140609001
Qualification of Alternate Assembly site for select WCSP devices
Change Notification / Sample Request

Date: 6/9/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140609001
Attachment: 1

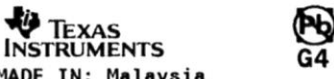

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AUP1T97YZPR	null
TPS22922BYFPR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140609001			PCN Date:	06/09/2014
Title:	Qualification of Alternate Assembly site for select WCSP devices				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	09/09/2014	Estimated Sample Availability:	Provided upon Request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>		Part number change		
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of JCAP as an alternate assembly site for the devices listed below. There is no material or dimensional differences between devices assembled at the 2 sites.					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
None					

Changes to product identification resulting from this PCN:		
Assembly Site		
STATS ChipPAC (SCS)	Assembly Site Origin (22L)	ASO: STS
JCAP	Assembly Site Origin (22L)	ASO: JCP
Sample product shipping label (not actual product label)		
  <div style="display: flex; justify-content: space-between;"> <div> <p>MSL 2 /260C/1 YEAR SEAL DT</p> <p>MSL 1 /235C/UNLIM 03/29/04</p> <p>OPT: 39</p> <p>ITEM: LBL: 5A (L)T0:1750</p> </div> <div> <p>(1P) SN74LS07NSR</p> <p>(Q) 2000 (D) 0336</p> <p>(31T) LOT: 3959047MLA</p> <p>(4W) TKY (1T) 7523483SI2</p> <p>(P)</p> <p>(2P) REV: (V) 0033317</p> <p>(20L) CSO: SHE (21L) CCO:USA</p> <p>(22L) ASO: MLA (23L) ACO: MYS</p> </div> </div>		
Topside Device marking:		
Assembly site code for STS= G		
Assembly site code for JCP= P		

Product Affected				
HPA02208YZPR	SN74AUP1T97YZPR	TPS22922BYFPR	TS5A22362YZPR	
HPA02302YZPR	SN74AVC2T45YZTR	TS5A22364YZPR		

Reference Qualification Data: (Approved: April 2008)				
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.				
Qualification Device: TS3DS26227YZT (MSL 1-260C)				
Package / Die Attributes				
Assembly Site & Bump Site:	JCAP	Bump Composition:	SnAgCu	
# Pins-Designator, Family:	12-YZT, DSBGA	Bump Diameter:	0.225mm	
Passivation/Coating:	MA21009085			
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail Lot#1 Lot#2 Lot#3		
**Steady-state Life Test	150C (168, 300 Hrs)	116/0	116/0	116/0
**High Temp. Storage Bake	170C (168, 420hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (500, 1000 Cyc)	77/0	77/0	77/0
Visual Mechanical	Per Manufacturing Specifications	Pass	Pass	Pass
Solderability	Steam age, 8 hours	Pass	Pass	Pass
Physical Dimensions	(per mechanical drawing)	Pass	Pass	Pass
Bump-shear	(per mfg. Site specification)	Pass	Pass	Pass
**Preconditioning: MSL1@260C				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com